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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





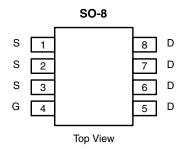






N-Channel 60 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | |
|---------------------|-----------------------------------|---------------------------------|-----------------------|--|--|--|
| V _{DS} (V) | $R_{DS(on)}(\Omega)$ Max. | I _D (A) ^a | Q _g (Typ.) | | | |
| | 0.0042 at V _{GS} = 10 V | 32.1 | | | | |
| 60 | 0.0054 at V _{GS} = 6 V | 28.3 | 18.8 nC | | | |
| | 0.0069 at V _{GS} = 4.5 V | 25 | | | | |



Ordering Information:

Si4062DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

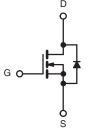
FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- DC/DC Primary Side Switch
- Industrial
- Synchronous Rectification
- Load Switch
- DC/DC Converters
- DC/AC Inverters



N-Channel MOSFET

| ABSOLUTE MAXIMUM RATIN | IGS (T _A = 25 °C | , unless othe | erwise noted) | |
|--|-----------------------------|-----------------------------------|----------------------|----|
| Parameter | Symbol | Limit | Unit | |
| Drain-Source Voltage | V _{DS} | 60 | V | |
| Gate-Source Voltage | | V_{GS} | ± 20 | V |
| | T _C = 25 °C | | 32.1 | |
| Continuous Drain Current /T 150 °C\ | T _C = 70 °C | 1 . — | 25.7 | |
| Continuous Drain Current (T _J = 150 °C) | T _A = 25 °C | l _D | 21.5 ^{b, c} | |
| | T _A = 70 °C | | 17 ^{b, c} | • |
| Pulsed Drain Current (t = 100 μs) | | I _{DM} | 150 | Α |
| | T _C = 25 °C | | 7 | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | - I _S - | 3.1 ^{b, c} | |
| Single Pulse Avalanche Current | | I _{AS} | 25 | |
| Avalanche Energy L = 0.1 mH | | E _{AS} | 31.2 | mJ |
| | T _C = 25 °C | | 7.8 | |
| Maximum Dawar Dissipation | T _C = 70 °C | 1 5 | 5 | w |
| Maximum Power Dissipation | T _A = 25 °C | P _D | 3.5 ^{b, c} | VV |
| | T _A = 70 °C | 1 | 2.2 ^{b, c} | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | °C |

| THERMAL RESISTANCE RATINGS | | | | | | |
|---|--------------|-------------------|---------|------|--------------|--|
| Parameter | Symbol | Typical | Maximum | Unit | | |
| Maximum Junction-to-Ambient ^{b, d} | t ≤ 10 s | R _{thJA} | 29 | 35 | °C/W | |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 13 | 16 | O/ VV | |

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 80 °C/W.

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| SPECIFICATIONS (T _J = 25 °C, unless otherwise noted) | | | | | | | |
|--|-------------------------|--|------|--------|--------|------------|--|
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 60 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | I _D = 250 μA | | 96 | | mV/°C | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | - I _D = 250 μA | | - 5.8 | | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_D = 250 \mu A$ | 1.4 | | 2.6 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA | |
| Zana Oaka Walka aa Bair O | Inno | V _{DS} = 60 V, V _{GS} = 0 V | | | 1 | <u>μ</u> Α | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 55 °C | | | 10 | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$ | 30 | | | Α | |
| | | $V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$ | | 0.0035 | 0.0042 | Ω | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 6 \text{ V}, I_D = 15 \text{ A}$ | | 0.0043 | 0.0054 | | |
| | | $V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$ | | 0.0055 | 0.0069 | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 20 A | | 80 | | S | |
| Dynamic ^b | | | | | • | | |
| Input Capacitance | C _{iss} | | | 3175 | | pF | |
| Output Capacitance | C _{oss} | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 1265 | | | |
| Reverse Transfer Capacitance | C _{rss} | | | 95 | | | |
| Total Gate Charge | 0 | $V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$ | | 40 | 60 | | |
| lotal Gate Charge | Q _g | | | 18.8 | 29 | | |
| Gate-Source Charge | Q_gs | $V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$ | | 8.9 | | | |
| Gate-Drain Charge | Q_gd | | | 3.8 | | | |
| Output Charge | Q _{oss} | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$ | | 51.5 | 80 | | |
| Gate Resistance | R_{g} | f = 1 MHz | 0.5 | 2 | 3 | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 52 | 100 | | |
| Rise Time | t _r | $V_{DD} = 30 \text{ V}, R_L = 3 \Omega$ | | 105 | 200 | ns | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$ | | 26 | 50 | | |
| Fall Time | t _f | | | 10 | 20 | | |
| Turn-On Delay Time | t _{d(on)} | | | 16 | 30 | 113 | |
| Rise Time | t _r | $V_{DD} = 30 \text{ V}, R_L = 3 \Omega$ | | 6 | 12 | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ | | 34 | 70 | | |
| Fall Time | t _f | | | 8 | 16 | | |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | | | 7.1 | | |
| Pulse Diode Forward Current $(t_p = 100 \mu s)$ | I _{SM} | | | | 150 | Α | |
| Body Diode Voltage | V _{SD} | I _S = 5 A | | 0.74 | 1.1 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 46 | 92 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | I _F = 5 A, di/dt = 100 A/μs, T _J = 25 °C | | 44 | 88 | nC | |
| Reverse Recovery Fall Time | t _a | $\frac{1}{1} = \frac{1}{1} = \frac{1}$ | | 20 | | ns | |
| Reverse Recovery Rise Time | t _b |] | | 26 | | | |

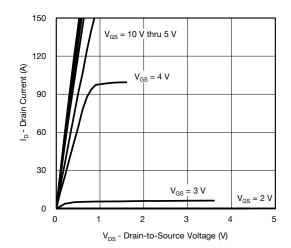
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %

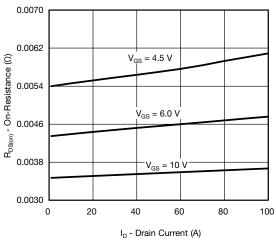
b. Guaranteed by design, not subject to production testing.



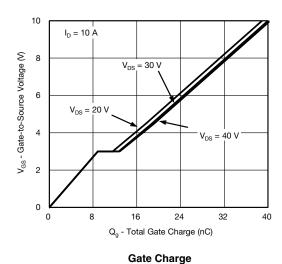
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

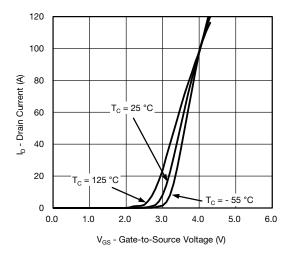


Output Characteristics

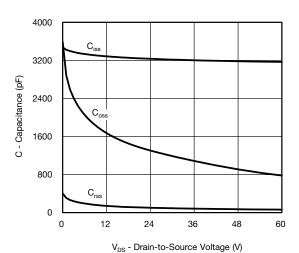


On-Resistance vs. Drain Current

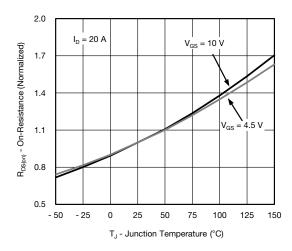




Transfer Characteristics



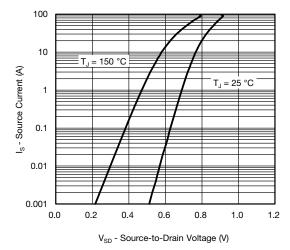
Capacitance



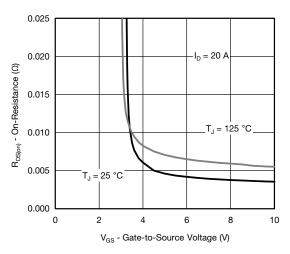
On-Resistance vs. Junction Temperature

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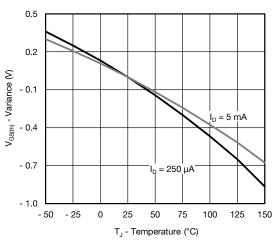
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



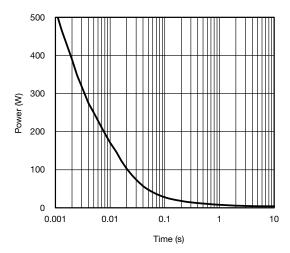
Source-Drain Diode Forward Voltage



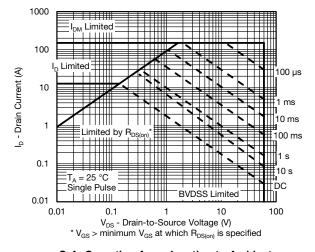
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



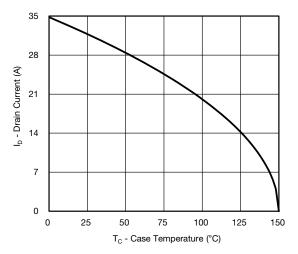
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

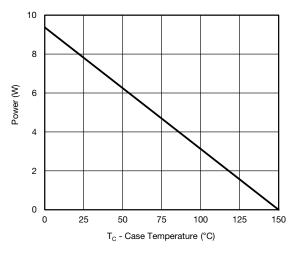


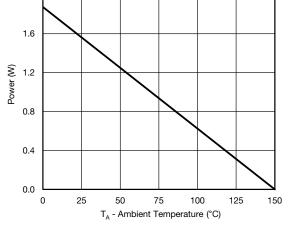
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*

2.0





Power, Junction-to-Foot

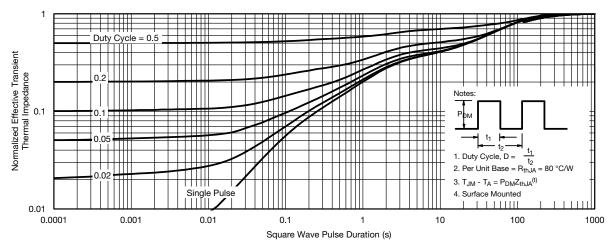
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

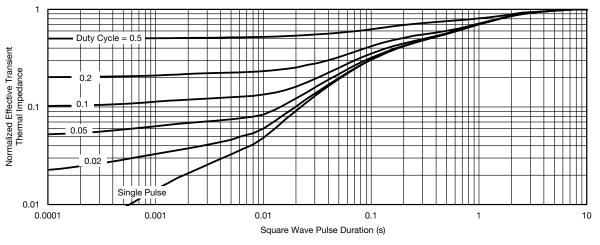
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

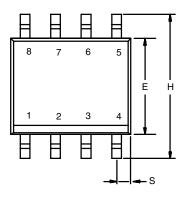


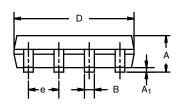
Normalized Thermal Transient Impedance, Junction-to-Foot

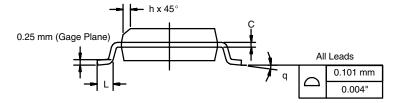
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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







| | MILLIM | IETERS | INCHES | | |
|--------------------------------|----------|--------|-----------|-------|--|
| DIM | Min | Max | Min | Max | |
| Α | 1.35 | 1.75 | 0.053 | 0.069 | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | |
| Е | 3.80 | 4.00 | 0.150 | 0.157 | |
| е | 1.27 BSC | | 0.050 BSC | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | |
| q | 0° | 8° | 0° | 8° | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | |
| ECN: C-06527-Rev. I. 11-Sep-06 | | | | | |

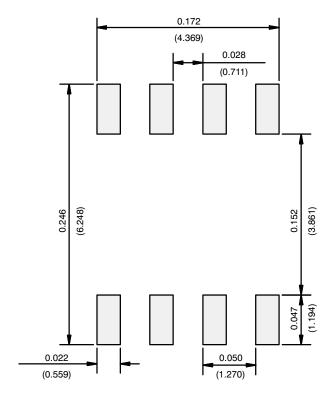
DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06

APPLICATION NOTE



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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